IN THE SPECIFICATION

Please amend the paragraph beginning at page 6, line 29 to read as follows. Please note that this paragraph previously was amended in the paper entitled "Response to Office Action Mailed March 12, 2003."

A die can then be attached to lead frame 10 of Fig. 2. Fig. 3A is a side view of a lead frame package 10-1 with a die 30, according to one embodiment. Die 30 is secured to ILTs 20 using a non-conductive film or die attach paste 32, with an inner lead trace (ILT) tape 33, such as a standard lead locking tape discussed above, placed on the bottom of ILT 20. Note that die 30 may also be secured to ILT tape 33 by film or paste 32 when tape 33 is placed on the top side 20a of ILTs 20 (see Fig. 3B). The ~~ends of~~ ILTs 20 are down set ~~or~~ and an outer portion of the ILT is vertically bent, such that a bottom surface of an outer end portion of the respective ILT adjacent the outer ~~ends~~ end will be exposed after die 10 has been encapsulated or packaged, such as with a conventional encapsulant or mold compound 34. The position of the inward remainder of the respective ILTs 20 can be on approximately the same plane as the external lead bond fingers, the die attach pad, or somewhere in between. The ~~ends of~~ ILTs 20 are down set during the manufacture of the lead frame, prior to the die assembly process. Bond pads 36 of die 30 and selected ones of ILTs 20 and OLTs 12 are wire-bonded, such as with thin conductive bond wires 35, to provide the desired signal routing or interconnections between the die and the ILTs and OLTs. The package can then be encased, such as with encapsulant or mold compound 34. The encapsulant 34 includes a top surface 34a, a bottom surface 34b, and side surfaces 34c vertically between the top and bottom surfaces 34a, 34b. The ILTs 20 have their inner and outer ends within a perimeter of encapsulant 34. OLTs 12 have an encapsulated inner portion 12a to which bond wires 35 are bonded, and an

unencapsulated outer portion 12b that extends from a peripheral side of encapsulant 34. The outer portion 12b is vertically bent so that a bottom surface portion the respective OLT 12 is approximately coplanar with the bottom of encapsulant 34 and the exposed bottom surface portion of ILTs 20. Portions of OLTs 12 and ILTs 20 are then attached to a printed circuit board (PCB) 37, such as with solder 38, to provide electrical connection between PCB 37 and die 30, via OLTs 12 and ILTs 20. Consequently, an increased number of inputs and outputs are possible to and from die 30.